CRXMH70P065NMG4AQ

SiC MOSFET 750V, 25m Ω , 70A

Features

- CRM G4 SIC MOSFET Technology
- High Blocking Voltage with Low On-Resistance
- High Speed Switching with Low Capacitances
- Avalanche Ruggedness
- Fast Reverse Recovery
- AEC-Q101 Qualified

Product Summary

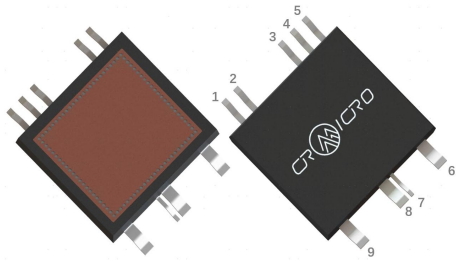
VDS	750V
$R_{DS(on)_typ}$	25m Ω
I_D	70A

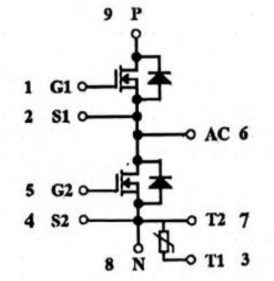
Applications

- Switching Mode Power Supply(SMPS)
- High Voltage DC/DC Converters
- On Board Charger(OBC)
- EV Charger

100% Avalanche Tested

RoHS HF





Package Marking and Ordering Information

Part #	Marking	Package	Packing	Qty
CRXMH70P065NMG4AQ	CRXMH70P065NMG4AQ	MSOP-9	Reel	200pcs

Absolute Maximum Ratings

Parameter	Symbol	Value	Unit
Drain-source voltage	V_{DS}	750	V
Continuous drain current V_{GS}=18V， T_C = 25°C V_{GS}=18V， T_C = 100°C	I_D	 70 50	A
Pulsed drain current (T_C = 25°C, t_p limited by T_{jmax})	$I_{D(pulse)}$	140	A
Avalanche energy, single pulse (L=10mH, Rg=25Ω)	E_{AS}	920	mJ
Gate-Source voltage (dynamic)[a1]	V_{GSmax}	-10/+22	V
Gate-Source voltage (static)[a2]	V_{GSop}	-5/+18	V
Power dissipation (T_C=25°C,T_J=175°C)	P_D	136	W
Operating Junction and Storage Temperature	T_j,T_{stg}	-55...175	°C

a1: When using MOSFET Body Diode V_{GSmax} = -5V/+22V

a2: MOSFET can also safely operate at 0/+18V

Thermal Resistance

Parameter	Symbol	Value	Unit
Thermal resistance, junction – case. Max	R_{thJC}	1.1	°C/W
Thermal resistance, junction – ambient. Max	R_{thJA}	35	

Electrical Characteristic (at Tj = 25 °C, unless otherwise specified)

Parameter	Symbol	Value			Unit	Test Condition
		min.	typ.	max.		
Static Characteristic						
Drain-source breakdown voltage	$V_{(BR)DSS}$	750	-	-	V	V_{GS}=0V, I_D=250uA
Gate threshold voltage	$V_{GS(th)}$	2	-	4	V	V_{DS}=V_{GS},I_D=10mA
Zero gate voltage drain current	I_{DSS}	-	0.1	100	μA	VDS=650V,VGS=0V T_j=25°C
		-	1	-		T_j=175°C
Gate-source leakage current	I_{GSS}	-	-	±100	nA	V_{GS}=-10/+22V,V_{DS}=0V
Drain-source on-state resistance	$R_{DS(on)}$	-	32	45	mΩ	VGS=15V, ID=23A, T_j=25°C
		-	34	-		T_j=175°C
Drain-source on-state resistance	$R_{DS(on)}$	-	25	35	mΩ	VGS=18V, ID=23A, T_j=25°C
		-	30	-		T_j=175°C
Transconductance	g_{fs}	-	19	-	S	VDS=20V,IDS=23A
Dynamic Characteristic						
Internal Gate resistance	$R_{G(int)}$	-	1.1	-	Ω	f=1MHz
Input Capacitance	C_{iss}	-	1777	-	pF	V_{GS}=0V, V_{DS}=650V, f=1MHz
Output Capacitance	C_{oss}	-	135	-		
Reverse Transfer Capacitance	C_{rss}	-	6.1	-		
Coss Stored Energy	E_{oss}	-	35	-	uJ	
Gate Total Charge	Q_g	-	78.4	-	nC	VGS=-5/18V VDS=400V ID=23A
Gate-Source charge	Q_{gs}	-	26.6	-		
Gate-Drain charge	Q_{gd}	-	10.4	-		
Turn-on delay time	$t_{d(on)}$	-	6.4	-	ns	VDD=400V,ID=23A VGS=-5V/18V, RG=2.5Ω, L=120uH
Rise time	t_r	-	9.6	-		
Turn-off delay time	$t_{d(off)}$	-	18	-		
Fall time	t_f	-	9	-		
Turn-On Switching Energy	$E_{(on)}$	-	85.2	-	uJ	
Turn Off Switching Energy	$E_{(off)}$	-	4.7	-		

Body Diode Characteristic

Parameter	Symbol	Value			Unit	Test Condition
		min.	typ.	max.		
Body Diode Forward Voltage	V_{SD}	-	3.7	-	V	VGS=0V,IF=11A
		-	3.2	-	V	VGS=0V,IF=11A, Tj=175℃
Continuous Diode Forward Current	I_S	-	-	70	A	V_{GS}=0V
Diode pulse Current	$I_{S,pulse}$	-	-	140	A	pulse width t_p limited by Tjmax
Body Diode Reverse Recovery Time	t_{rr}	-	24.3	-	ns	di/dt=1000A/us IF=23A Vdd=400V Tj=25℃
Body Diode Reverse Recovery Charge	Q_{rr}	-	270	-	nC	
Body Diode Peak Reverse Recovery Current	I_{rrm}	-	18.7	-	A	
Body Diode Reverse Recovery Time	t_{rr}	-	45	-	ns	di/dt=1000A/us IF=23A Vdd=400V, Tj=175℃
Body Diode Reverse Recovery Charge	Q_{rr}	-	420	-	nC	
Body Diode Peak Reverse Recovery Current	I_{rrm}	-	20	-	A	

Typical Performance Characteristics

Fig 1. Output Characteristics (Tj=-55℃)

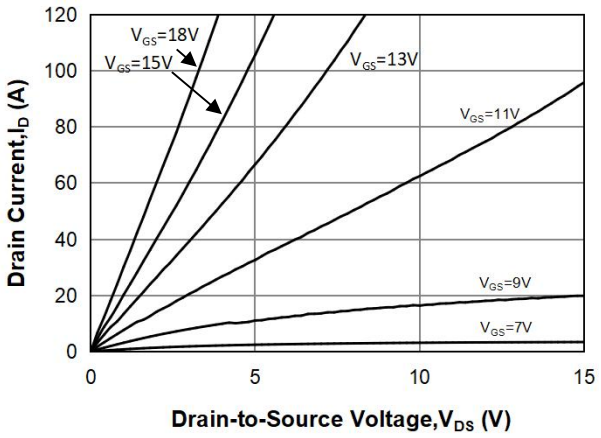


Fig 2. Output Characteristics (Tj=25℃)

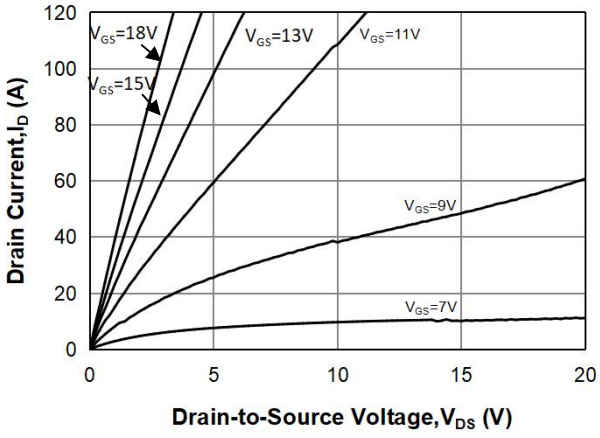


Fig 3. Output Characteristics (Tj=175℃)

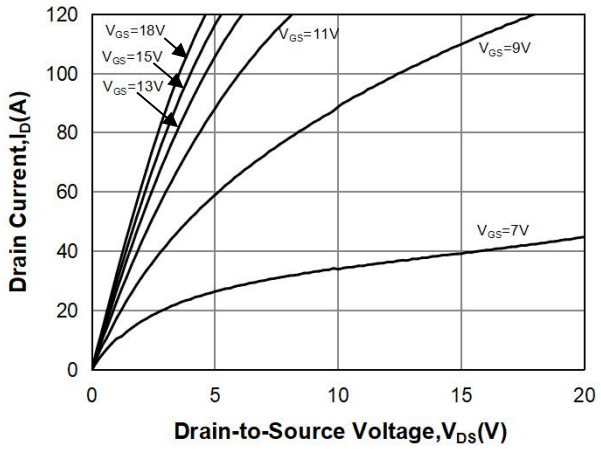


Fig 4: Rds(on) vs. Temperature

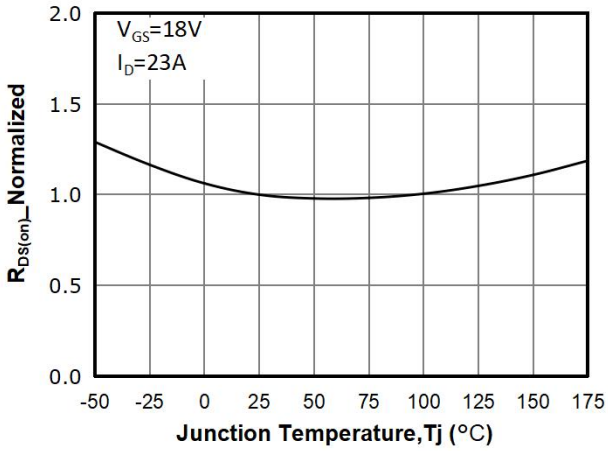


Fig 5: On-Resistance vs. Drain Current For Various Temperatures

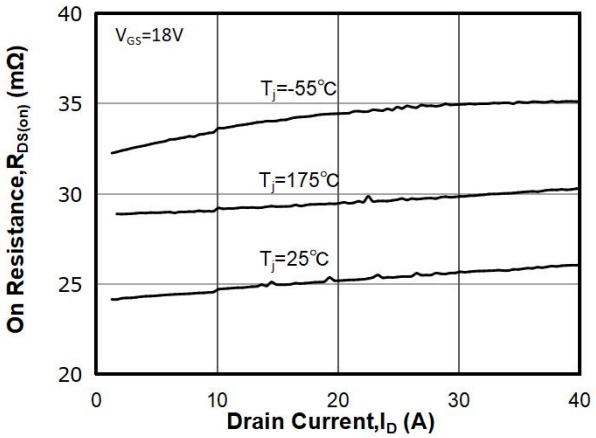


Fig 6: Rds(on) vs. Temperature For Various Gate Voltage

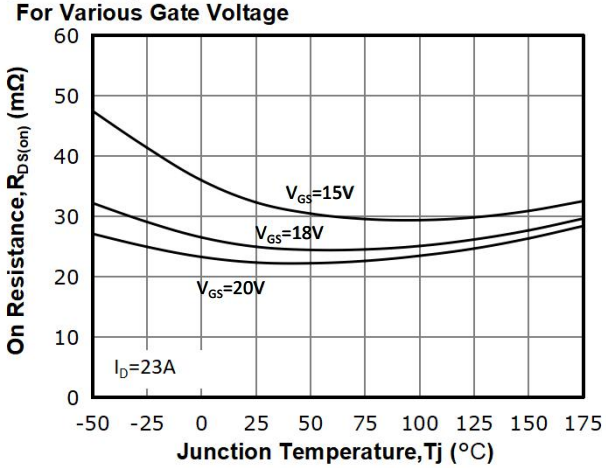


Fig 7: Transfer Characteristics

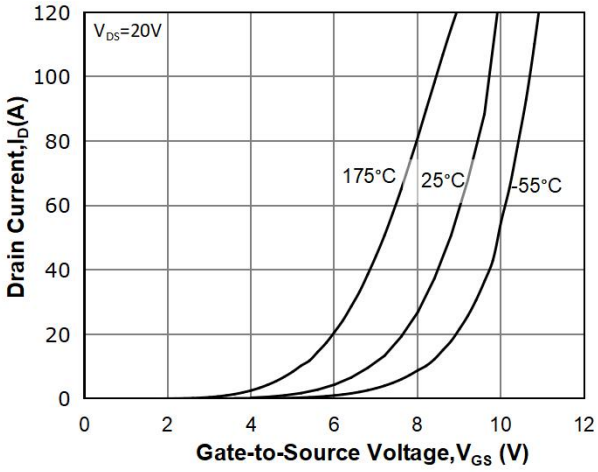


Fig 8: Body-diode Forward Characteristics For Various Temperatures

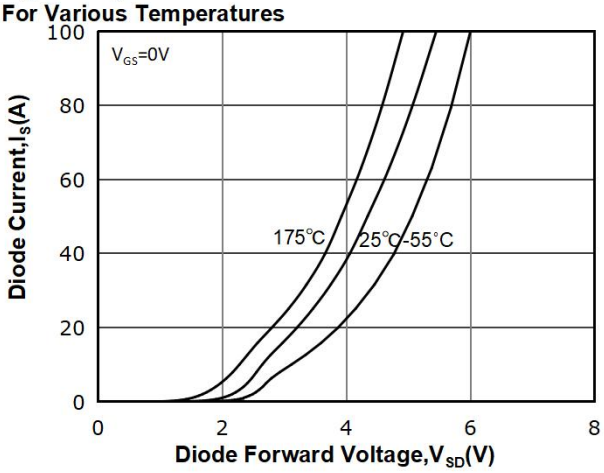


Fig 9: VGS(th) Vs Tj Characteristics

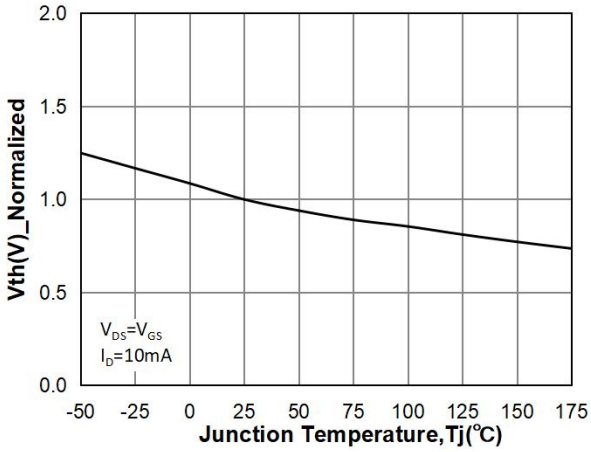


Fig 10: 3rd Quadrant Characteristic at 25℃

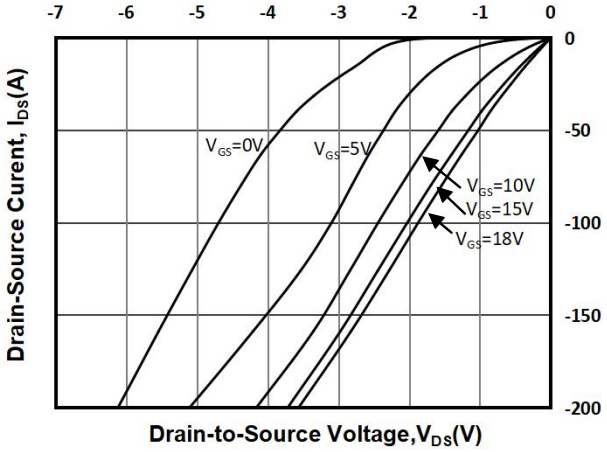


Fig 11：Gtate Charge Characteristics

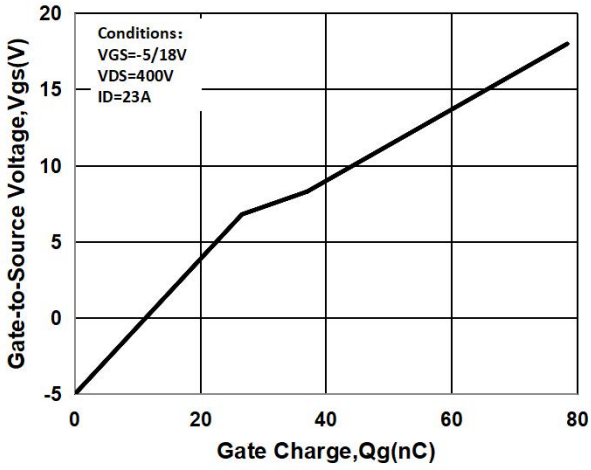


Fig 12: Capacitance Characteristics

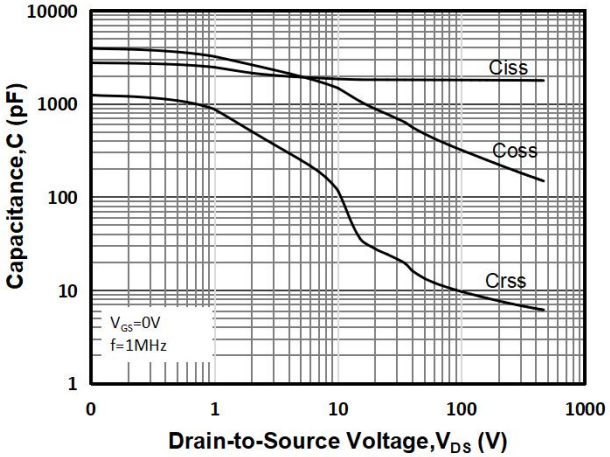


Fig 13: Continuous Drain Current vs. Case Temperature

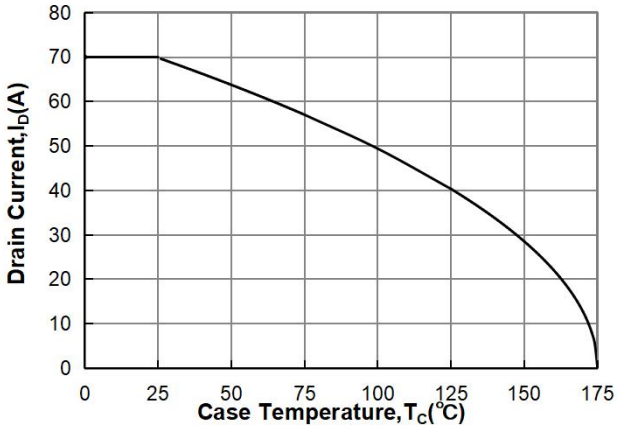


Fig 14: Maximum Power Dissipation vs. Case Temperature

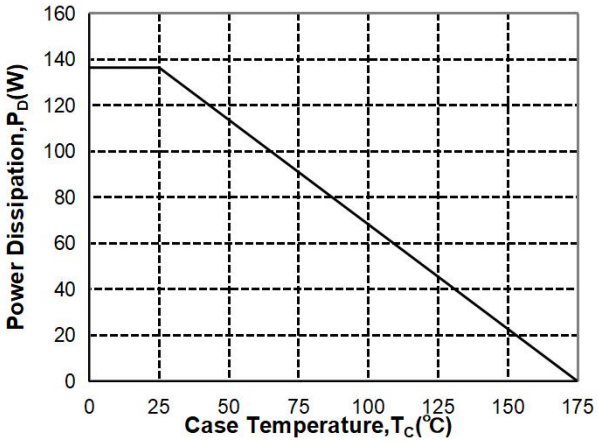


Fig 15: Safe Operating Area

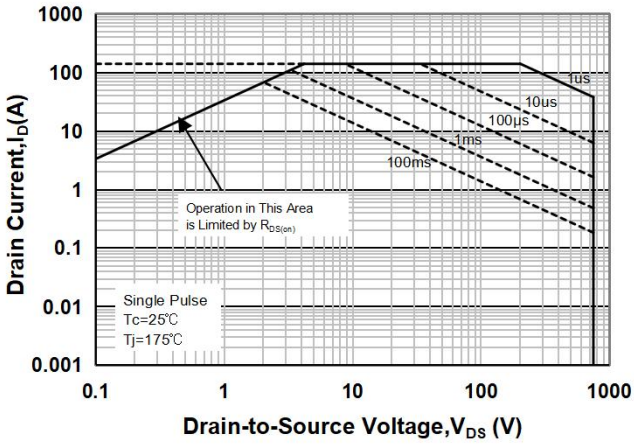


Fig 16:Output Capacitor Stored Energy

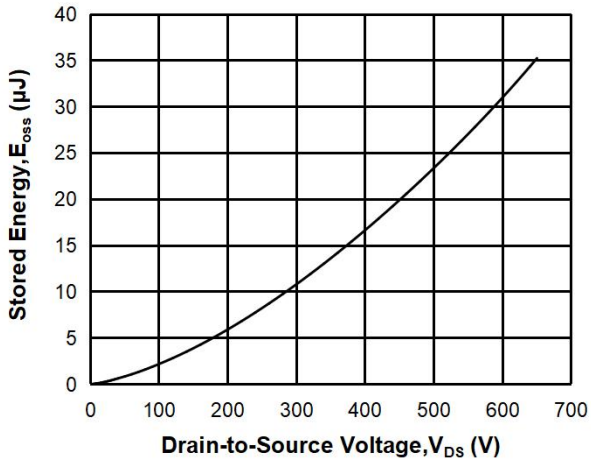


Fig 17: Max. Transient Thermal Impedance

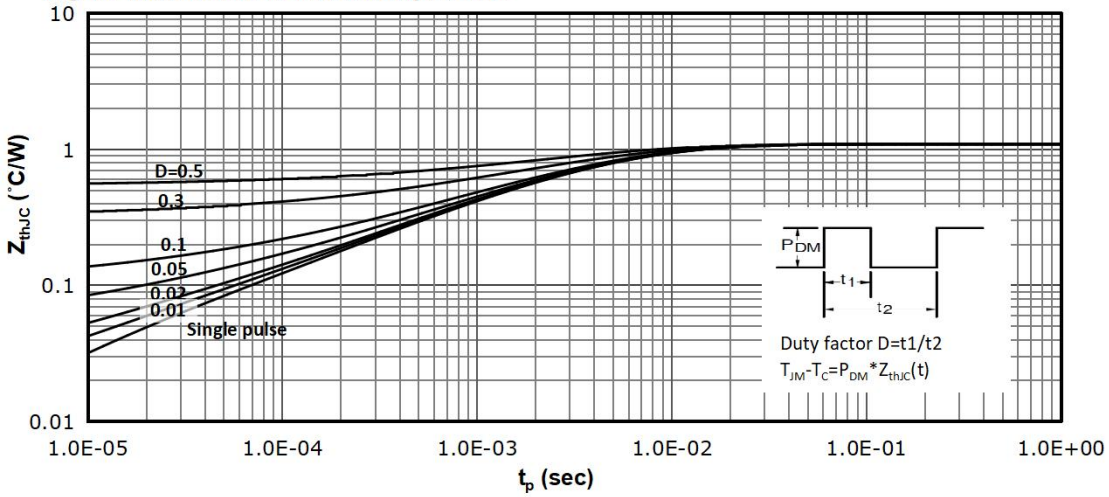


Fig 18: Rg(Ω) vs. Switching Times(us)

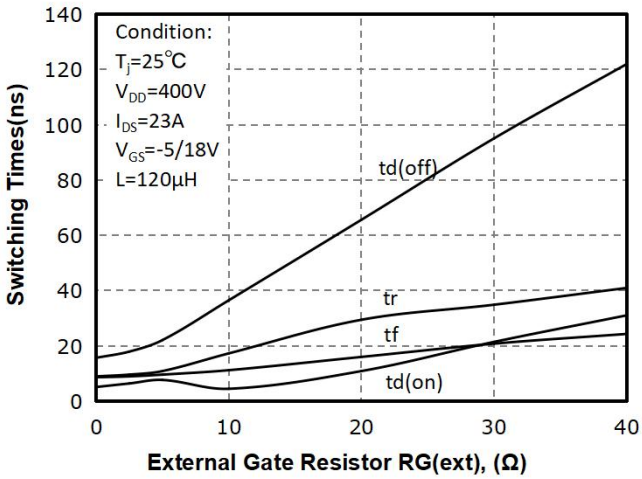


Fig 19: Rg(Ω) vs. Switching Loss(uJ)

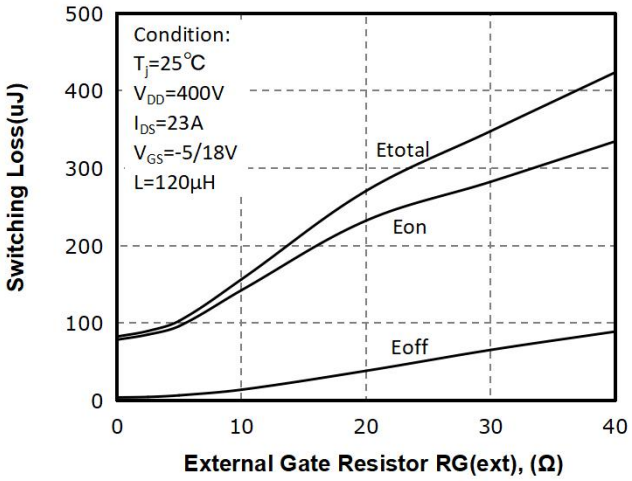


Fig 20: Temperature(°C) vs. Switching Loss(uJ)

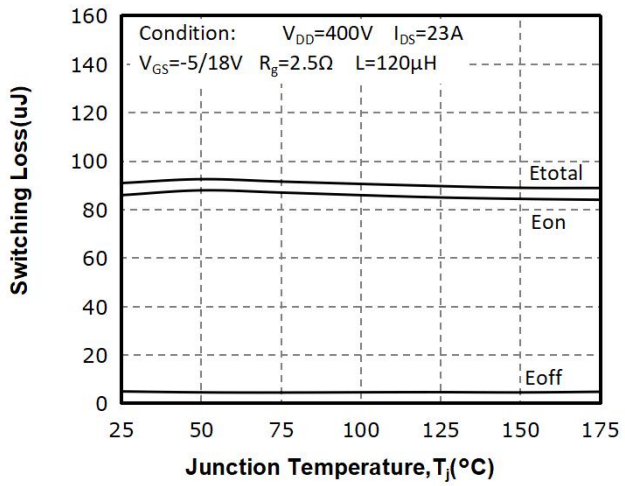
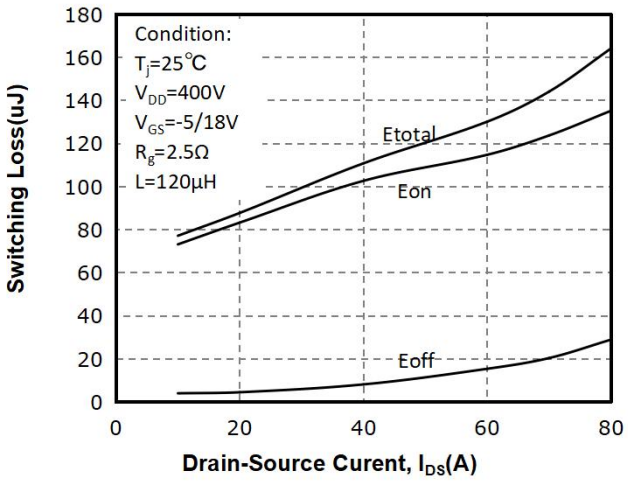
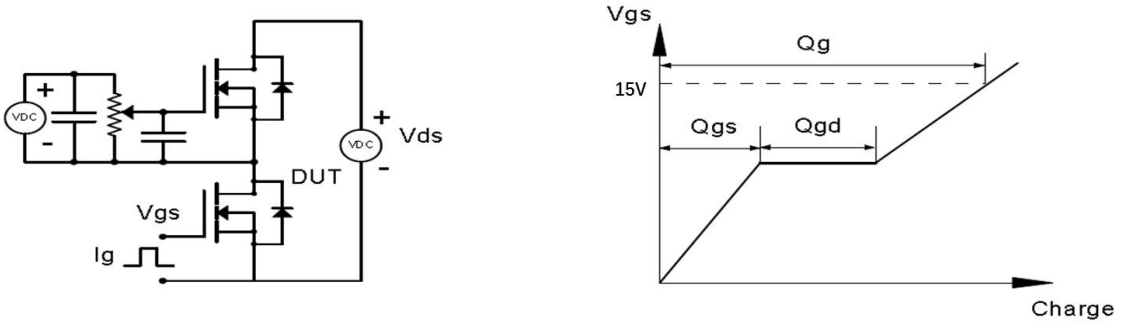


Fig 21: I_{DS}(A) vs. Switching Loss(uJ)

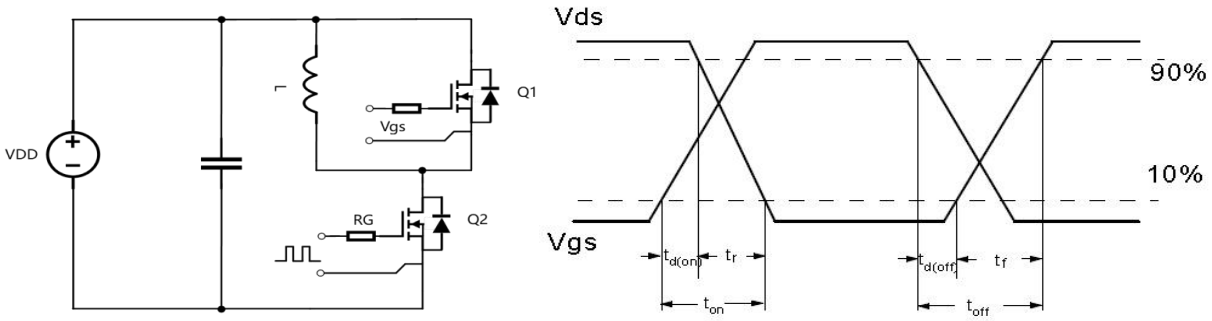


Test Circuit & Waveform

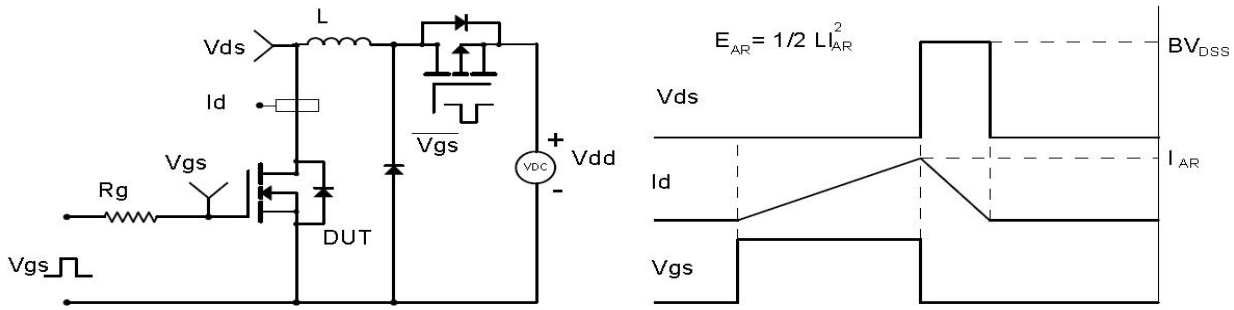
Gate Charge Test Circuit & Waveform



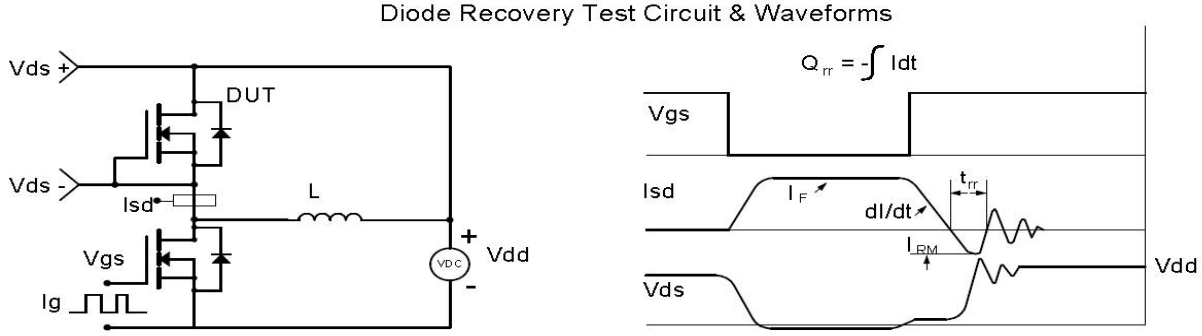
Resistive Switching Test Circuit & Waveforms



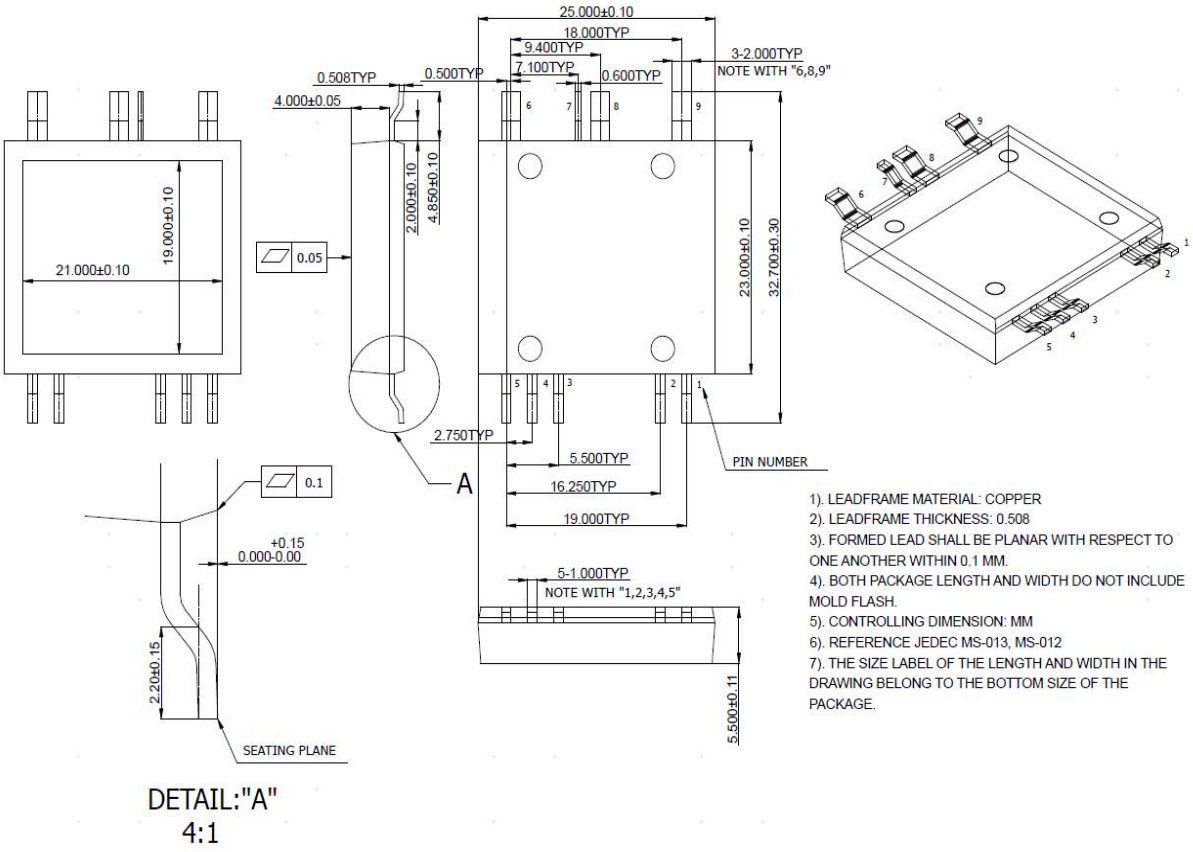
Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms



Package Outline: IPM-MSOP9



1). LEADFRAME MATERIAL: COPPER
2). LEADFRAME THICKNESS: 0.508
3). FORMED LEAD SHALL BE PLANAR WITH RESPECT TO ONE ANOTHER WITHIN 0.1 MM.
4). BOTH PACKAGE LENGTH AND WIDTH DO NOT INCLUDE MOLD FLASH.
5). CONTROLLING DIMENSION: MM
6). REFERENCE JEDEC MS-013, MS-012
7). THE SIZE LABEL OF THE LENGTH AND WIDTH IN THE DRAWING BELONG TO THE BOTTOM SIZE OF THE PACKAGE.

Revision History

Revison	Date	Major changes
1.0	2026/3/23	Release of formal version

Disclaimer

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• The information given in this document shall in no event be regarded as a guarantee of conditions or characteristics .The data contained in this document is exclusively intended for technically trained staff. It is the responsibility of customer's technical departments to evaluate the suitability of the product for the intended application and the completeness of the product information given in this document with respect to such application.

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